

#### description/ordering information

#### **ORDERING INFORMATION**

ТА	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			SN74ALS245A-1N	SN74ALS245A-1N
	PDIP – N	Tube	SN74ALS245AN	SN74ALS245AN
			SN74AS245N	SN74AS245N
		Tube	SN74ALS245ADW	ALS245A
0°C to 70°C		Tape and reel	SN74ALS245ADWR	AL3243A
	SOIC - DW	Tube	SN74ALS245A-1DW	ALS245A-1
	50IC - DW	Tape and reel	SN74ALS245A-1DWR	AL5245A-1
		Tube	SN74AS245DW	AS245
		Tape and reel	SN74AS245DWR	A3245
		Tape and reel	SN74ALS245ANSR	ALS245A
	SOP – NS	Tape and reel	SN74ALS245A-1NSR	ALS245A-1
		Tape and reel	SN74AS245NSR	74AS245
	SSOP – DB	Tape and reel	SN74ALS245ADBR	G245A
	CDIP – J	Tube	SNJ54ALS245AJ	SNJ54ALS245AJ
	CDIF = J	Tube	SNJ54AS245J	SNJ54AS245J
–55°C to 125°C	CFP – W	Tube	SNJ54ALS245AW	SNJ54ALS245AW
	LCCC – FK	Tube	SNJ54ALS245AFK	SNJ54ALS245AFK
		Tube	SNJ54AS245FK	SNJ54AS245FK



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright  $\circledast$  2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

#### description/ordering information(continued)

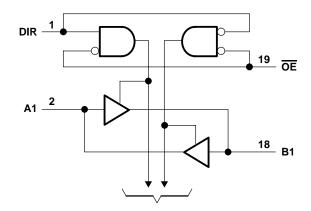
These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable  $\overline{(OE)}$  input can be used to disable the device so that the buses are effectively isolated.

The -1 version of the SN74ALS245A is identical to the standard version, except that the recommended maximum  $I_{OL}$  is increased to 48 mA. There is no -1 version of the SN54ALS245A.

	FUNCTION TABLE										
INP	UTS	OPERATION									
OE	DIR	OPERATION									
L	L	B data to A bus									
L	Н	A data to B bus									
н	Х	Isolation									

#### logic diagram, each gate (positive logic)



**To Seven Other Channels** 

# absolute maximum ratings over operating free-air temperature range (SN54ALS245A, SN74ALS245A) (unless otherwise noted)<sup>†</sup>

Supply voltage Vee		
		5.5 V
		e
	DW package	ge 58°C/W
	N package	
	NS package	e 60°C/W
Storage temperature range		–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

#### recommended operating conditions (see Note 2)

		SNS	54ALS24	5A	SN7	4ALS24	5A	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			-12			-15	mA	
				12			24	~^^	
IOL	Low-level output current						48†	mA	
ТА	Operating free-air temperature	-55		125	0		70	°C	

 $^{+}$  Applies only to the -1 version and only if V<sub>CC</sub> is between 4.75 V and 5.25 V

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CO	DITIONS	SN5	4ALS24	5A	SN7	4ALS24	5A	LINUT
	PARAMETER	TEST CO	NDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	lj = – 18 mA			-1.5			-1.5	V
		$V_{CC}$ = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> –2			V <sub>CC</sub> -2			
Vон			I <sub>OH</sub> = -3 mA	2.4	3.2		2.4	3.2		V
VOH	$V_{CC} = 4.5 V$	$I_{OH} = -12 \text{ mA}$	2						v	
			I <sub>OH</sub> = -15 mA				2			
			I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	
VOL	$V_{CC} = 4.5 V$	I <sub>OL</sub> = 24 mA					0.35	0.5	V	
			$I_{OL} = 48 \text{ mA}^{\dagger}$					0.35	0.5	
ı.	Control inputs	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 7 V			0.1			0.1	mA
łı	A or B ports	VCC = 5.5 V	V <sub>I</sub> = 5.5 V			0.1			0.1	ША
	Control inputs	V <sub>CC</sub> = 5.5 V,	VI = 2.7 V			20			20	
ΙΗ	A or B ports§	VCC = 3.3 V,	V   - 2.7 V		20				20	μA 0
i	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>1</sub> = 0.4 V			-0.1			-0.1	mA
۱L	A or B ports§	VCC = 5.5 V,	V] = 0.4 V			-0.1			-0.1	ША
ю¶		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		30	48		30	45	
ICC	СС	$V_{CC} = 5.5 V$	Outputs low		36	60		36	55	mA
			Outputs disabled		38	63		38	58	

<sup>†</sup> Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

<sup>‡</sup> All typical values are  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

§ For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.



SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CI R1 R2	_ = 50 p 1 = 500 9 2 = 500 9	Ω,	Ι,	UNIT
		SN54ALS245A SN74ALS245					
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	B or A	1	19	3	10	
<sup>t</sup> PHL	AUID	BUIA	1	14	3	10	ns
<sup>t</sup> PZH	OE	A or B	2	30	5	20	ns
<sup>t</sup> PZL	ÛE	AOID	2	29	5	20	115
<sup>t</sup> PHZ	OE	A or B	2	14	2	10	ns
<sup>t</sup> PLZ	UE	7010	2	30	4	15	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# absolute maximum ratings over operating free-air temperature range (SN54AS245, SN74AS245) (unless otherwise noted)<sup>‡</sup>

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub> : All inputs	
I/O ports	5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 2)

		SN	154AS24	15	SN	SN74AS245		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
I <sub>ОН</sub>	High-level output current			-12			-15	mA
IOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CON		SI	154AS24	15	SN	174AS24	15	LINUT	
	PARAMETER	TEST CON	DITIONS	MIN	түр†	MAX	MIN	түр†	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	lı = – 18 mA			-1.2			-1.2	V	
		$V_{CC}$ = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2			
Vон			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		v	
⊻ОН		V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						v	
			I <sub>OH</sub> = -15 mA	A		2					
V <sub>OL</sub>		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA		0.3	0.55				v	
		VCC = 4.5 V	I <sub>OL</sub> = 64 mA					0.35	0.55	v	
ı.	Control inputs	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 7 V			0.1			0.1	mA	
lı	A or B ports	VCC = 3.5 V	VI = 5.5 V			0.1			0.1	IIIA	
ı	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>1</sub> = 2.7 V			50			20	μA	
ΙН	A or B ports <sup>‡</sup>	VCC = 3.3 V,	v   = 2.7 v		70				70	μΛ	
1	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>1</sub> = 0.4 V			-0.5			-0.5	mA	
۱Ľ	A or B ports‡	VCC = 3.5 V,	v] = 0.4 v		-0.75				-0.75	IIIA	
۱ <sub>0</sub> §		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-50		-150	-50		-150	mA	
			Outputs high		62	97		62	97		
ICC		$V_{CC} = 5.5 V$	Outputs low		95	143		95	143	mA	
			Outputs disabled		79	123		79	123	1	

<sup>†</sup> All typical values are V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.
<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.
§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I<sub>OS</sub>.

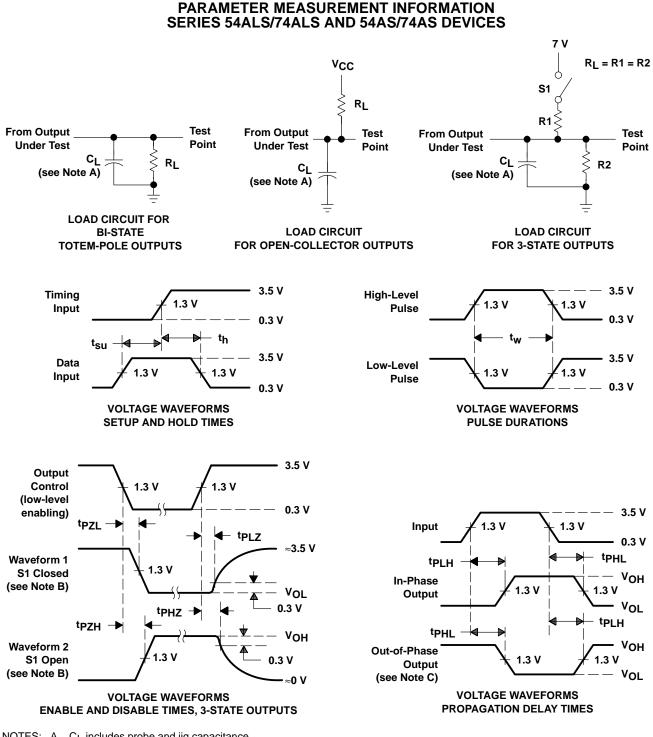
#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> CL R1 R2 T <sub>A</sub>	V,	UNIT		
		SN54AS245 SN74AS245					
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	B or A	2	9.5	2	7.5	20
<sup>t</sup> PHL	AUB	BUIA	2	9	2	7	ns
<sup>t</sup> PZH		A or B	2	11	2	9	ns
tPZL	OE	AUIB	2	10.5	2	8.5	115
<sup>t</sup> PHZ	OE	A or B	2	7.5	2	5.5	20
t <sub>PLZ</sub>	UE	AUD	2	12	2	9.5	ns

<sup>¶</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

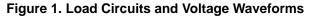


SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics:  $PRR \le 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.







21-Dec-2018

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84030012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
8403001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
8403001SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SN54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS245AJ	Samples
SN54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS245J	Samples
SN74ALS245A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples



### PACKAGE OPTION ADDENDUM

21-Dec-2018

Orderable Device	Status	Package Type		Pins			Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS245AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	Samples
SN74ALS245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74AS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	Samples
SN74AS245N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS245N	Samples
SN74AS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	Samples
SNJ54ALS245AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
SNJ54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
SNJ54ALS245AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SNJ54AS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 245FK	Samples
SNJ54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS245J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



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21-Dec-2018

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 :

- Catalog: SN74ALS245A, SN74AS245
- Military: SN54ALS245A, SN54AS245

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS245A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245A-1NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ALS245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS245ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AS245NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

TEXAS INSTRUMENTS

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## PACKAGE MATERIALS INFORMATION

22-Dec-2018



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS245A-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245A-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS245ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS245ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS245NSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

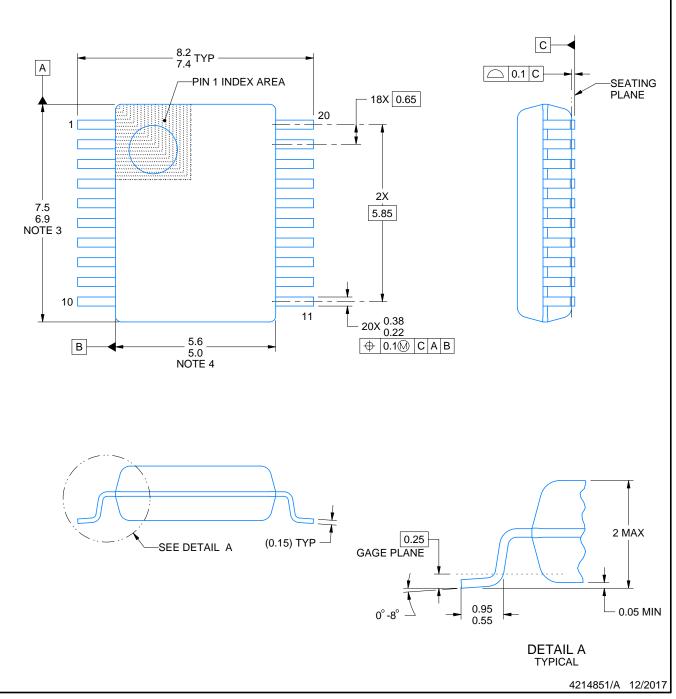
# **DB0020A**



# **PACKAGE OUTLINE**

### TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.

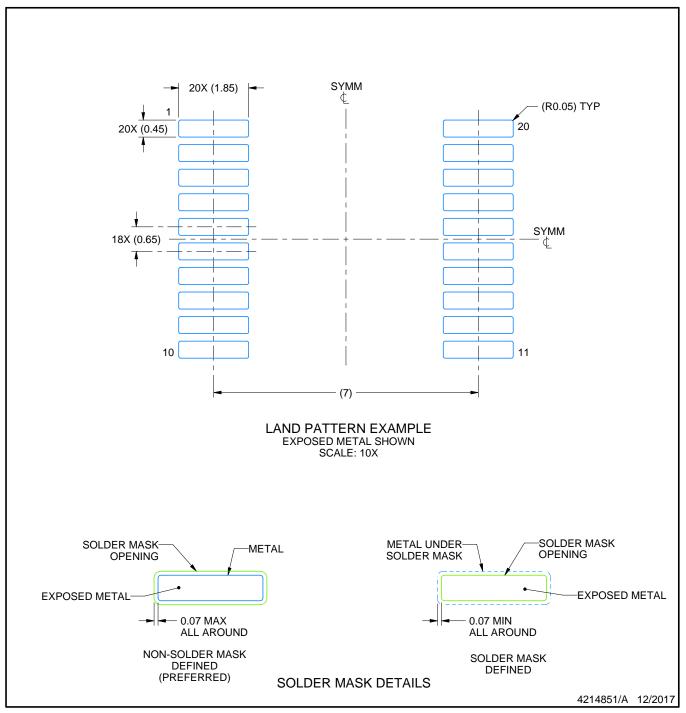


# DB0020A

# **EXAMPLE BOARD LAYOUT**

### TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

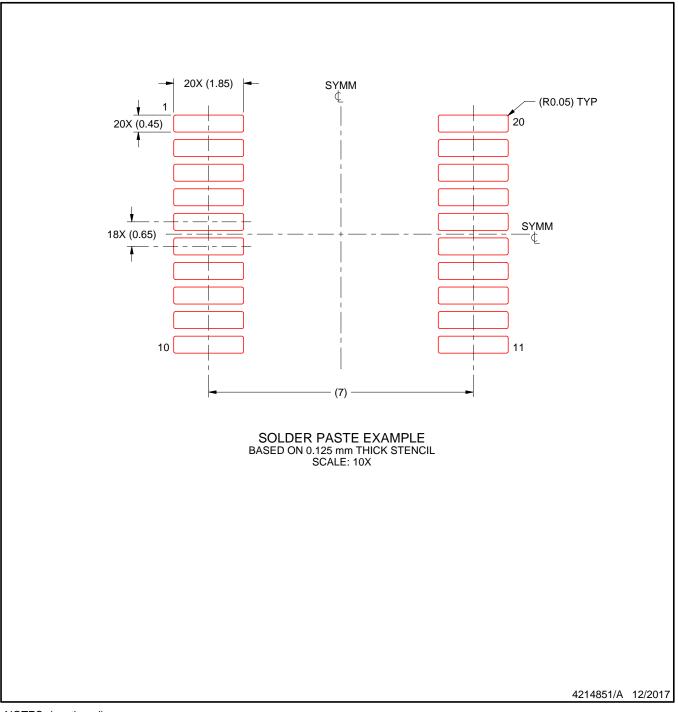


# DB0020A

# **EXAMPLE STENCIL DESIGN**

### TSSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



# **DW0020A**



# **PACKAGE OUTLINE**

### SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



# DW0020A

# **EXAMPLE BOARD LAYOUT**

### SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# DW0020A

# **EXAMPLE STENCIL DESIGN**

### SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice. В.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
    D. Index point is provided on cap for terminal identification only.
    E. Falls within Mil-Std 1835 GDFP2-F20



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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